

FY2023 Q1 Financial Results Briefing

Aug 4, 2023



MEIKO ELECTRONICS CO., LTD.
(Securities Identification Code: 6787)

This presentation contains forward-looking statements concerning Meiko Group's future plans, strategies and performance. However, Meiko does not publish this presentation as a disclosure document based on the Financial Instruments and Exchange Act of Japan.

These forward-looking statements are not historical facts, rather they represent assumptions and beliefs based on comprehensive data currently available.

Furthermore, the Printed Circuit Board business is subject to a number of risks and uncertainties that relate to raw material price, conditions of customers' market, technological trends, change of foreign exchange, change of tax rules and regulations, disasters, international conflicts and other factors. Meiko therefore wishes to caution that actual results may differ materially from our expectations.

FY2023 Q1 Financial Results - Consolidated

(100 million yen)

	FY2022 Q1 Results	FY2023 Q1 Results	Year-on-Year amount	Year-on-Year %
Net Sales	400	416	16	3.9%
Operating Income	28 7.0%	※ 9 2.2%	-19	-67.7%
Ordinary Income	52 13.0%	29 7.0%	-23	-43.6%
Net Income	40 9.9%	23 5.5%	-17	-42.8%
Average FX rate (JPY/USD)	131.24	139.63		

※ Including approx. ¥800 allowance for doubtful accounts

Net Sales and Operating Income by Product Application (100million yen)

	FY2022 Q1 Results		FY2023 Q1 Results		Year-on-Year	
	Net Sales	Operating Income %	Net Sales	Operating Income %	Net Sales %	Operating Income %
Automotive	202	16 7.9%	211	13 6.2%	9 4.5%	-3 -18.8%
Smartphone/ Table	72	7 9.7%	49	-8 -16.3%	-23 -31.9%	-15 -214.3%
Semiconductor Package			1	-2 -200.0%	1 -	-2 -
SSD/ IoT Module	23	2 8.7%	17	0 0.0%	-6 -26.1%	-2 -100.0%
AI appliances/ Amusement/ Other Substrate	70	3 4.3%	50	2 4.0%	-20 -28.6%	-1 -33.3%
EMS/ODM	33	0 0.0%	88	4 4.5%	55 166.7%	4 -
Total	400	28 7.0%	416	9 2.2%	16 3.9%	-19 -67.7%

Net Sales by Product Specification

(100 million yen)

■ MLB
 ■ HDI PCB
 ■ Flexible PCB
 ■ High Dissipation PCB
 ■ Semiconductor Package
 ■ Other substrates
 ■ EMS/ODM

